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Applicant(s): Choi et al.

Docket No.

END920020007US1

Serial No.  
10/078,020

Filing Date  
2/15/2002

Examiner  
Zimmerman, John J.

Group Art Unit  
1775

Invention: LEAD-FREE TIN-SILVER-COPPER ALLOY SOLDER COMPOSITION

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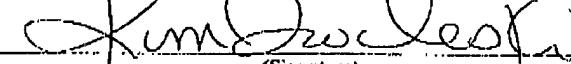
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Applicant: Choi *et al.*

Examiner: Zimmerman, John J.

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Serial No.: 10/078,020

Att Unit: 1775

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For: **LEAD-FREE TIN-SILVER-COPPER ALLOY SOLDER COMPOSITION**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

AMENDMENT

Sir:

In response to the Office Action mailed October 2, 2003, please amend the above-identified application as follows:

10/078,020

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